

# **1.5A Three Terminal Adj. Voltage Regulator**

### Description

The SG117HV and SG117AHV are 3-terminal positive adjustable voltage regulators which offer a higher input voltage range. They are capable of supplying in excess of 0.5A or 1.5A over an output voltage range of 1.25V to 57V, utilizing an input supply voltage up to 60V. A major feature of the SG117AHV is a reference voltage tolerance guaranteed within  $\pm$  1%, allowing an overall power supply tolerance to be better than 3% using inexpensive 1% resistors. Line and load regulation performance has been improved as well.

Moreover, the SG117AHV reference voltage is guaranteed not to exceed 2% when operating over the full load, line and power dissipation conditions. The SG117AHV adjustable regulators offer an improved solution for all positive voltage regulator requirements with load currents up to 1.5A.

In addition to replacing many fixed regulators, the SG117HV/AHV can be used in a variety of other applications due to its 'floating' design as long as the input-to-output differential maximum is not exceeded, such as a current source.

# Features

- Adjustable Output Down to 1.25V
- 1% Output Voltage Tolerance
- 0.01%/V Line Regulation
- 0.3% Load Regulation
- Min. 1.5A Output Current
- Typical 80dB Ripple Rejection
- Available in Hermetic TO-257

# High Reliability Features – SG117HV

- Available to MIL-STD-883
- MSC-AMSG level "S" Processing Available
- Available to DSCC
  - Standard Microcircuit Drawing (SMD)

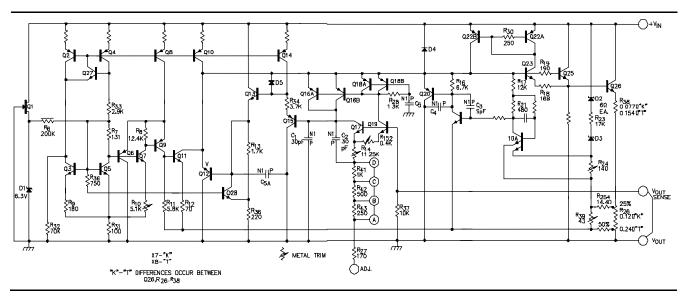


Figure 1 - Block Diagram

### Schematic Diagram



# **Connection Diagrams and Ordering Information**

Ambient Temperature	Туре	Package	Part Number	Packaging Type	Connection Diagram	
			SG117AHVK-883B		ADJUSTMENT	
-55°C to	к	3-TERMINAL METAL CAN	SG117AHVK	TO-3		
125°C	IX.		SG117HVK-883B			
			SG117HVK		V <sub>IN</sub>	
			SG117AHVT-883B			
-55°C to	т	3-TERMINAL METAL CAN	SG117AHVT	TO-39		
125°C	I		SG117HVT-883B		ADJUST O <sup>2</sup> O <sup>3</sup> V <sub>OUT</sub>	
			SG117HVT			
	IG	3-Pin HERMETIC Package	SG117AHVIG-883B	HERMETIC TO-257	Case is Isolated	
-55°C to			SG117AHVIG			
125°C			SG117HVIG-883B			
		(Isolated)	SG117HVIG		Case is isolated	
	G	3-Pin HERMETIC Package	SG117AHVG-883B	HERMETIC TO-257		
-55°C to			SG117AHVG			
125°C			SG117HVG-883B		Case is V <sub>OUT</sub>	
			SG117HVG			
			SG117AHVL-883B		N.C. 0 N.C. 0 N.	
EE°C to		20-Pin Ceramic	SG117AHVL	Ceramic (LCC) Leadless Chip Carrier	N.C. be or N.C. ADJUST bă ∾Q N.C.	
-55°C to 125°C	L		SG117HVL-883B		N.C. b☆	
			SG117HVL		100 N C C C	
<i>Notes:</i> 1. Contact factory for JAN and DESC part availability.						

All parts are viewed from the top.

3. For devices with multiple inputs and outputs both must be externally connected together at the device terminals.

4. For normal operation, the SENSE pin must be externally connected to the load.

Figure 2 · Connection Diagrams and Ordering Information



# Absolute Maximum Ratings

Parameter	Value	Units
Power Dissipation	Internally Limited	
Input to Output Voltage Differential	60	V
Operating Junction Temperature	-65 to 150	°C
Lead Temperature (Soldering, 10 seconds)	300	°C
Notes: Exceeding these ratings could cause damage to the davice. All voltages a	no with norm out to Chound Co	

Exceeding these ratings could cause damage to the device. All voltages are with respect to Ground. Currents are positive into, negative out of specified terminal.

# **Thermal Data**

Parameter	Value	Units
K Package: 3 Terminal TO-3 Metal Can		•
Thermal Resistance-Junction to Case, $\theta_{JC}$	3	°C/W
Thermal Resistance-Junction to Ambient, $\theta_{JA}$	35	°C/W
T Package: 3-Pin TO-39 Metal Can		
Thermal Resistance-Junction to Case, $\theta_{JC}$	15	°C/W
Thermal Resistance-Junction to Ambient, $\theta_{JA}$	120	°C/W
IG Package: 3-Pin TO-257 Hermetic (Isolated)		
Thermal Resistance-Junction to Case, $\theta_{JC}$	3.5	°C/W
Thermal Resistance-Junction to Ambient, $\theta_{JA}$	42	°C/W
G Package: 3-Pin TO-257 Hermetic		
Thermal Resistance-Junction to Case, $\theta_{JC}$	3.5	°C/W
Thermal Resistance-Junction to Ambient, θ <sub>JA</sub>	42	°C/W
L Package: 20-Pin Ceramic (LCC) Leadless		•
Thermal Resistance-Junction to Case, $\theta_{JC}$	35	°C/W
Thermal Resistance-Junction to Ambient, $\theta_{JA}$	120	°C/W
Notes:		1

Notes

1. Junction Temperature Calculation:  $T_J = T_A + (P_D x \theta_{JA})$ .

2. The above numbers for  $\theta_{JC}$  are maximums for the limiting thermal resistance of the package in a standard mounting configuration. The  $\theta_{JA}$  numbers are meant to be guidelines for the thermal performance of the device/pcboard system. All of the above assume no ambient airflow.

# **Recommended Operating Conditions**

Parameter	Value	Units				
Input Voltage Range	8 to 40	V				
Operating Ambient Temperature Range						
SG117AHV / SG117HV	55 to 125	°C				
Note: Range over which the device is functional.						



# **Electrical Characteristics**

Unless otherwise specified, these characteristics apply over the full operating ambient temperature for the SG117AHV / SG117HV with -55°C  $\leq$  T<sub>A</sub>  $\leq$  125°C, V<sub>IN</sub> – V<sub>OUT</sub> = 5.0V and for I<sub>OUT</sub> = 500mA (K, G, and IG) and I<sub>OUT</sub> = 100mA (T, and L packages). Although power dissipation is internally limited, these specifications are applicable for power dissipations of 2W for the T, and L packages, and 20W for the K, G, and IG packages. I<sub>MAX</sub> is 1.5A for the K, G, and IG packages and 500mA for the T, and L packages. Low duty cycle pulse testing techniques are used which maintains junction and case temperatures equal to the ambient temperature.

_		SG117AHV			SG117HV			Units
Parameter	Test Condition	Min	Тур	Max	Min	Тур	Max	
Reference Section								
	I <sub>OUT</sub> = 10mA, T <sub>A</sub> = 25°C	1.238	1.250	1.262				V
Reference Voltage	$\begin{array}{l} 3V \leq (V_{IN} - V_{OUT}) \leq 60V, \\ P \leq P_{MAX} \\ 10mA \leq I_{OUT} \leq I_{MAX} \end{array}$	1.225	1.250	1.270	1.20	1.25	1.30	V
Output Section								
	$3V \leq (V_{IN} - V_{OUT}) \leq 60V,$ I <sub>L</sub> = 10mA							
Line Regulation	T <sub>A</sub> = 25°C		0.005	0.01		0.01	0.02	%/V
	$T_A = T_{MIN}$ to $T_{MAX}$		0.01	0.02		0.02	0.05	%/V
	10mA <u>&lt;</u> I <sub>OUT</sub> <u>&lt;</u> I <sub>MAX</sub>							
	$V_{OUT} \leq 5V, T_A = 25^{\circ}C$		5	15		5	15	mV
Load Regulation <sup>1</sup>	V <sub>OUT</sub> > 5V, T <sub>A</sub> = 25°C		0.1	0.3		0.1	0.3	%
	V <sub>OUT</sub> ≤ 5V		20	50		20	50	mV
	V <sub>OUT</sub> > 5V		0.3	1		0.3	1	%
Thermal Regulation <sup>2</sup>	T <sub>A</sub> = 25°C, 20ms pulse		0.002	0.02		0.03	0.07	%/W
Ripple Rejection	V <sub>OUT</sub> = 10V, f = 120Hz							
	$C_{ADJ} = 1\mu F$ , $T_A = 25^{\circ}C$		65			65		dB
	$C_{ADJ} = 10 \mu F$	66	80		66	80		dB
Minimum Load Current	$(V_{IN} - V_{OUT}) = 60V$		3.5	7		3.5	7	mA
Current Limit	$(V_{IN} - V_{OUT}) \leq 15V$							
	K, P, G, IG Packages	1.5	2.2		1.5	2.2		Α
	T, L Packages	0.5	0.8		0.5	0.8		Α
	$(V_{IN} - V_{OUT}) = 60V, T_J = 25^{\circ}C$							
	K, P, G, IG Packages		0.3			0.3		Α
	T, L Packages		0.1			0.1		Α
Temperature Stability <sup>2</sup>			1	2		1		%
Long Term Stability <sup>2</sup>	T <sub>A</sub> = 125°C, 1000 Hours		0.3	1		0.3	1	%
RMS Output Noise (% of $V_{OUT}$ ) <sup>2</sup>	T <sub>A</sub> = 25°C, 10Hz <u>≤</u> f <u>≤</u> 10kHz		0.001			0.001		%
Adjust Section	1	1	1	1		1	n	1
Adjust Pin Current			50	100		50	100	μA
Adjust Pin Current Change	$10mA < I_{OUT} < I_{MAX},$ $2.5V < (V_{IN} - V_{OUT}) < 60V$		0.2	5		0.2	5	μA
due to heating effects are of	t constant junction temperature, usin covered under the specification for th gh guaranteed, are not tested in proc	ermal reg		low duty	v cycle. (	Changes i	n output	voltag



### **Characteristic Curves**

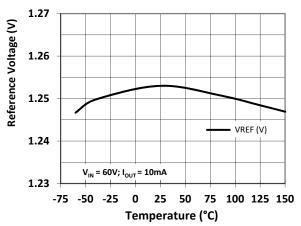


Figure 3 - Reference Voltage vs. Temperature

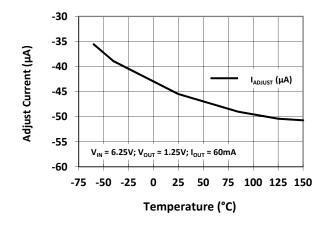


Figure 5 - Adjust Current vs. Temperature

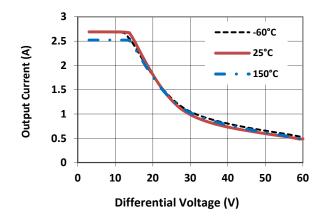


Figure 7 · Output Current vs. Input / Output Differential Voltage for K, P, G, IG Packages

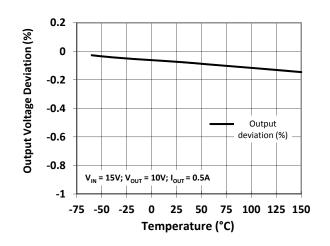


Figure 4 - Output Voltage Deviation vs. Temperature

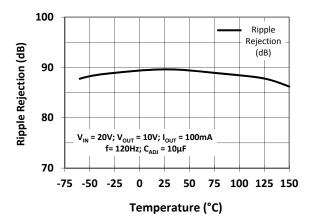


Figure 6 - Ripple Rejection vs. Temperature

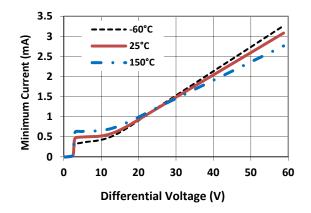
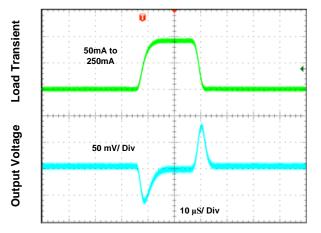


Figure 8 - Minimum Current vs. Input / Output Differential Voltage

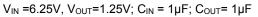


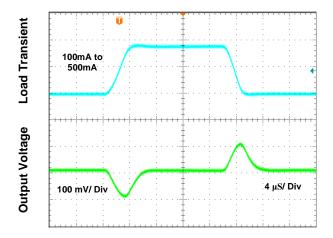
## **Characteristic Curves**

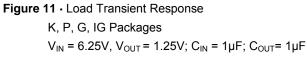


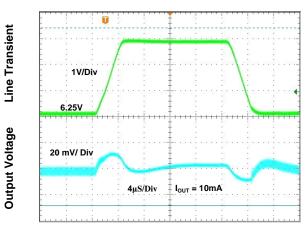


T, L, Packages



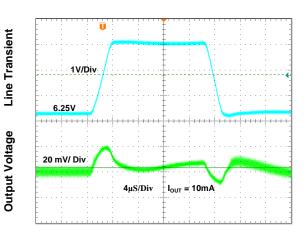








T, L, Packages V<sub>IN</sub> =6.25V, V<sub>OUT</sub>=1.25V; C<sub>IN</sub> = 1μF; C<sub>OUT</sub>= 1μF





K, P, G, IG Packages

 $V_{\text{IN}}$  = 6.25V,  $V_{\text{OUT}}$  = 1.25V;  $C_{\text{IN}}$  = 1 $\mu\text{F};$   $C_{\text{OUT}}\text{=}$  1 $\mu\text{F}$ 



### **Application Information**

#### General

The SG117AHV develops a 1.25V reference voltage between the output (OUT) and the adjust (ADJ) terminals (see Basic Regulator Circuit). By placing a resistor,  $R_1$  between these two terminals, a constant current is caused to flow through  $R_1$  and down through  $R_2$  to set the overall output voltage. Normally this current is the specified minimum load current of 5mA or 10mA. It is important to maintain this minimum output load current requirement otherwise the device may fail to regulate, and the output voltage may rise.

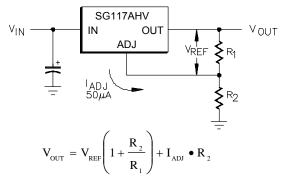


Figure 13 - Basic Regulator Circuit

The  $I_{ADJ}$  current does add an error to the output divider ratio, however because  $I_{ADJ}$  is very small and constant when compared with the current through R1, it represents a small error and can often be ignored.

It is easily seen from the above equation, that even if the resistors were of exact value, the accuracy of the output is limited by the accuracy of  $V_{REF}$ . With a guaranteed 1% reference, a 5V power supply design, using ±2% resistors, would have a worse case manufacturing tolerance of ± 4%. If 1% resistors were used, the tolerance would drop to ± 2.5%. A plot of the worst case output voltage tolerance as a function of resistor tolerance is shown below.

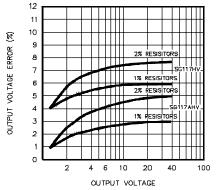
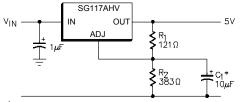


Figure 14 · Voltage Tolerance vs. Resistor Tolerance

#### **Bypass Capacitors**

Input bypassing using a 0.1  $\mu$ F ceramic or 1 $\mu$ F solid tantalum is recommended, and especially when any input filter capacitors are more than 5 inches from the device. A 0.1 $\mu$ F bypass capacitor on the ADJ pin is required if the load current varies by more than 1A/ $\mu$ sec. Improved ripple rejection (80dB) can be accomplished by adding a 10 $\mu$ F capacitor from the ADJ pin to ground.



 $^*$ C<sub>l</sub> Improves Ripple Rejection. X<sub>C</sub> should be small compared to R<sub>2</sub>.

Figure 15 · Improving Ripple Rejection



While the SG117HV is stable with no output capacitor, for improved AC transient response and to prevent the possibility of oscillation due to an unknown reactive load, a  $1\mu$ F capacitor is also recommended at the output. Because of their low impedance at high frequencies, the best type of capacitor to use is solid tantalum; ceramic capacitors may also be used. When bypass capacitors are used, it may be necessary to provide external protection diodes to prevent this external large capacitance from discharging through internal low current paths, which may damage the device. Although the duration of any surge current is short, there may be sufficient energy to damage the regulator. This is particularly true of the large capacitance on the ADJ pin when output voltages are higher than 25V. Such a capacitor could discharge into the ADJ pin when either the input or output is shorted. See example Use of Protection Diodes.

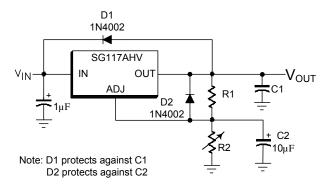


Figure 16 · Use of Protection Diodes

#### Load Regulation

Because the SG117AHV is a three-terminal device, it is not possible to provide true remote load sensing. Load regulation will be limited by the resistance of the wire connecting the regulator to the load. From the data sheet specification, regulation is measured at the bottom of the package. Negative side sensing is a true Kelvin connection, with the bottom of the output divider returned to the negative side of the load. Although it may not be immediately obvious, best load regulation is obtained when the top of the divider is connected directly to the case, not to the load. This is illustrated in (Connections for Best Load Regulation). If R1 were connected to the load, the effective resistance between the regulator and the load would be:

$$\mathbf{R}_{p} \bullet \left(\frac{\mathbf{R}_{2} + \mathbf{R}_{1}}{\mathbf{R}_{1}}\right), \mathbf{R}_{p} = \text{Parasitic Line Resistance}$$

Connected as shown,  $R_P$  is not multiplied by the divider ratio.  $R_P$  is about 0.004 $\Omega$  per foot using 16 gauge wire. This translates to 4mV/ft. at 1A load current, so it is important to keep the positive lead between regulator and load as short as possible.

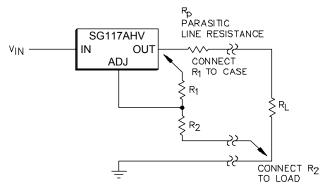


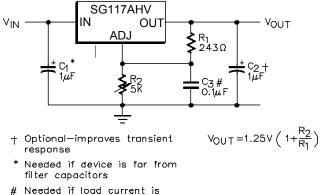
Figure 17 · Connections for Best Load Regulation



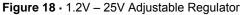
### **Current Limit**

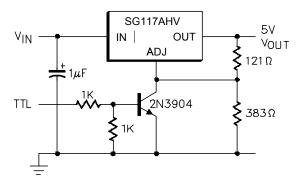
As outlined in the Electrical Characteristics the current limit will activate whenever the output current exceeds the specified levels. It is also important to bear in mind that the regulator includes a foldback-current characteristic that limits the current at higher  $V_{IN}$  to  $V_{OUT}$  differential voltages. This power limiting characteristic will prevent the regulator from providing full output current depending on the  $V_{IN}$  to V= differential. Also if during a short circuit situation the regulator was presented with a voltage that exceeds the Absolute Maximum Rating of 60V (e.g.  $V_{IN} > 60V$ ,  $V_{OUT} = 0V$ ) the device may fail, or be permanently damaged.

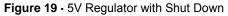
### **Typical Applications**

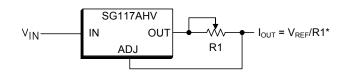


mechanically switched









\* 0.8 Ohms  $\leq R1 \leq 120$  Ohms

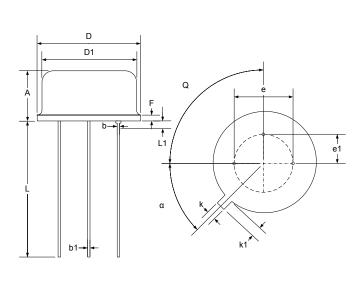
Figure 20 ·

Figure 21 - Programmable Current Limiter



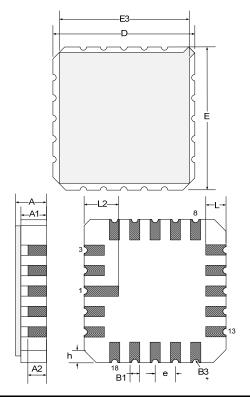
# PACKAGE OUTLINE DIMENSIONS

Controlling dimensions are in inches, metric equivalents are shown for general information.



Dim	MILLIM	ETERS	INCHES		
Dim	MIN	MAX	MIN	MAX	
D	8.89	9.40	0.350	0.370	
D1	8.13	8.51	0.320	0.335	
А	4.19	4.70	0.165	0.185	
b	0.41	0.48	0.016	0.019	
F	-	1.02	-	0.040	
е	5.08 BSC		0.200 BSC		
k	0.71	0.86	0.028	0.034	
k1	0.74	1.14	0.029	0.045	
L	12.70	14.48	0.500	0.570	
α	45° 1	ΓYΡ	45°	TYP	
e1	2.54 TYP		0.10	) TYP	
b1	0.41	0.53	0.016	0.021	
Q	90° 1	ΓYΡ	90°	TYP	
L1	-	1.27	-	0.50	

Figure 22 • T 3-Pin Metal Can TO-39 Package Dimensions



Dim	MILLIM	ETERS	INCHES		
Dim	MIN	MAX	MIN	MAX	
D/E	8.64	9.14	0.340	0.360	
E3	-	8.128	-	0.320	
е	1.270	BSC	0.050	) BSC	
B1	0.635	TYP	0.02	5 TYP	
L	1.02	1.52	0.040	0.060	
А	1.626	2.286	0.064	0.090	
h	1.016	1.016 TYP		0 TYP	
A1	1.372	1.68	0.054	0.066	
A2	-	1.168	-	0.046	
L2	1.91	2.41	0.075	0.95	
B3	0.203R		0.008R		

#### Note:

1. All exposed metalized area shall be gold plated 60 micro-inch minimum thickness over nickel plated unless otherwise specified in purchase order.

Figure 23 - L 20-Pin Ceramic Leadless Chip Carrier (LCC) Package Dimensions

MIN

0.185

0.035

0.115

0.027

0.645

0.410

0.410

0.500

0.527

0.140

0.202

INCHES

0.100 BSC

0.055 TYP

MAX

0.205

0.045

0.125

0.032

0.660

0.430

0.420

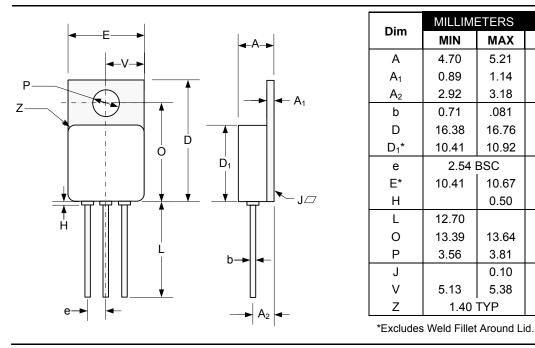
0.020

0.537

0.150

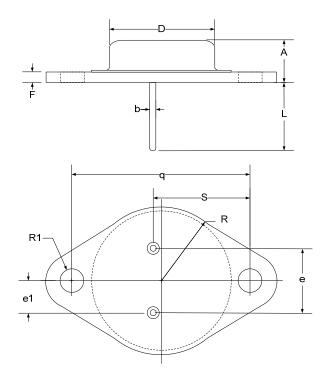
0.004

0.212



# PACKAGE OUTLINE DIMENSIONS

Figure 24 · G/IG 3-Pin Hermetic TO-257 Package Dimensions



	Dim	MILLIM	ETERS	INCHES		
	Dim	MIN	MAX	MIN	MAX	
Γ	А	6.86	7.62	0.270	0.300	
	q	29.90	30.40	1.177	1.197	
	b	0.97	1.09	0.038	0.043	
	D	19.43	19.68	0.765	0.775	
	S	16.64	17.14	0.655	0.675	
	е	10.67	11.18	0.420	0.440	
	E1	5.21	5.72	0.205	0.225	
	F	1.52	2.03	0.060	0.080	
	R1	3.84	4.09	0.151	0.161	
	L	10.79	12.19	0.425	0.480	
	R	12.57	13.34	0.495	0.525	

Figure 25 · K 3-Pin TO-3 Package Dimensions



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